



PHOTOCOUPLER PS2703-1

HIGH ISOLATION VOLTAGE HIGH COLLECTOR TO EMITTER VOLTAGE TYPE SOP MULTI PHOTOCOUPLER

–NEPOC Series–

DESCRIPTION

The PS2703-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

This is mounted in a plastic SOP (Small Outline Package) for high density applications.

This package has shield effect to cut off ambient light.

FEATURES

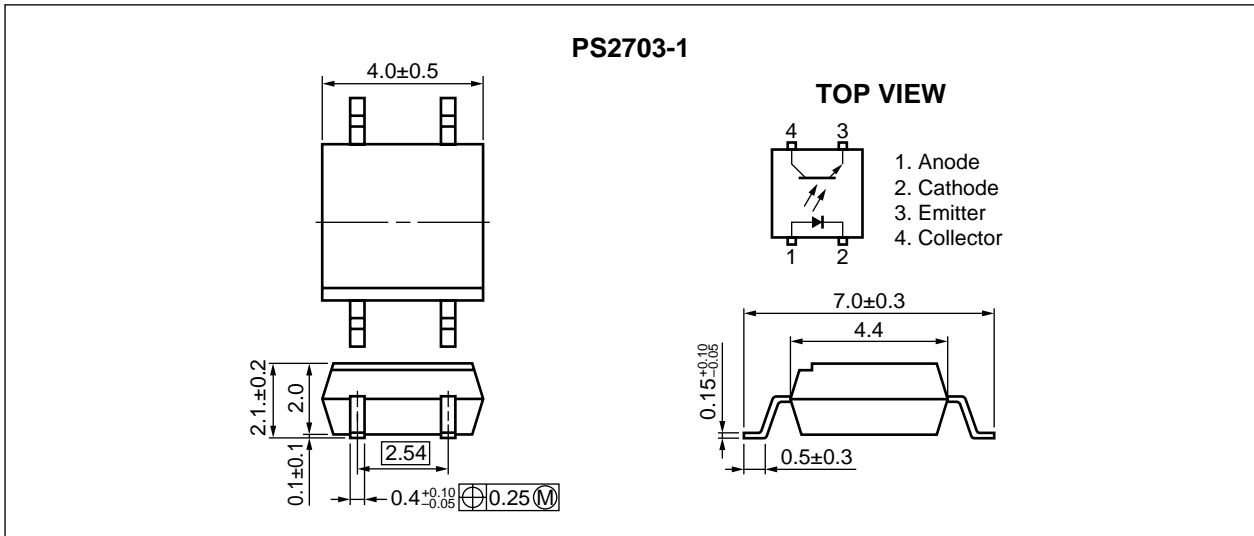
- High isolation voltage ($BV = 3\,750\text{ Vr.m.s.}$)
- High collector to emitter voltage ($V_{CE0} = 120\text{ V}$)
- SOP (Small Outline Package) type
- Each isolated channel per package
- High-speed switching ($t_r, t_f = 10\ \mu\text{s TYP.}$)
- Taping product number: PS2703-1-F3, F4
- ★ Safety standards
 - UL approved: File No. E72422
 - BSI approved: File No. 8219/8220
 - CSA approved: File No. CA 101391
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

APPLICATIONS

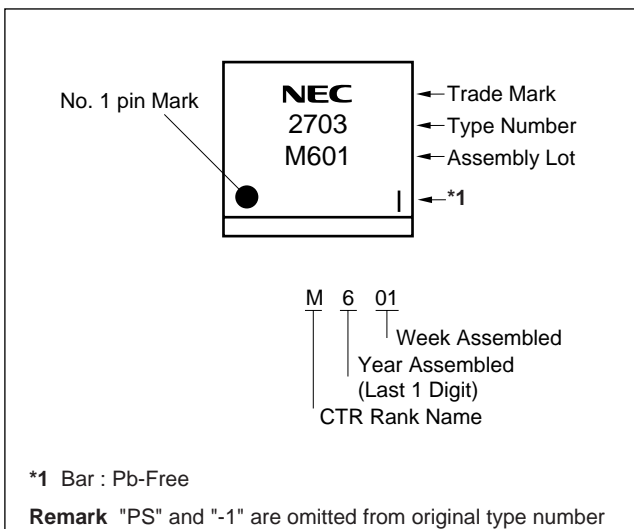
- Hybrid IC
- Telephone/FAX
- FA/OA equipment
- Programmable logic controllers
- Power supply

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PACKAGE DIMENSIONS (in millimeters)



★ **MARKING EXAMPLE**



★ **ORDERING INFORMATION**

| Part Number | Order Number | Solder Plating Specification | Packing Style | Safety Standard Approval | Application Part Number ^{*1} |
|---------------|-----------------|------------------------------|------------------------------|--|---------------------------------------|
| PS2703-1 | PS2703-1-A | Pb-Free | Magazine case 100 pcs | Standard products (UL, BSI, CSA approved) | PS2703-1 |
| PS2703-1-F3 | PS2703-1-F3-A | | Embossed Tape 3 500 pcs/reel | | |
| PS2703-1-F4 | PS2703-1-F4-A | | | | |
| PS2703-1-V | PS2703-1-V-A | | Magazine case 100 pcs | DIN EN60747-5-2 | |
| PS2703-1-V-F3 | PS2703-1-V-F3-A | | Embossed Tape 3 500 pcs/reel | (VDE0884 Part2) | |
| PS2703-1-V-F4 | PS2703-1-V-F4-A | | | Approved (Option) | |

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

| Parameter | | Symbol | Ratings | Unit |
|---------------------------------|------------------------------------|---------------------|-------------|---------|
| Diode | Forward Current (DC) | I _F | 50 | mA |
| | Reverse Voltage | V _R | 6 | V |
| | Power Dissipation Derating | ΔP _D /°C | 0.8 | mW/°C |
| | Power Dissipation | P _D | 80 | mW |
| | Peak Forward Current ^{*1} | I _{FP} | 1 | A |
| Transistor | Collector to Emitter Voltage | V _{CEO} | 120 | V |
| | Emitter to Collector Voltage | V _{ECO} | 6 | V |
| | Collector Current | I _C | 30 | mA |
| | Power Dissipation Derating | ΔP _C /°C | 1.5 | mW/°C |
| | Power Dissipation | P _C | 150 | mW |
| Isolation Voltage ^{*2} | | BV | 3 750 | Vr.m.s. |
| Operating Ambient Temperature | | T _A | -55 to +100 | °C |
| Storage Temperature | | T _{stg} | -55 to +150 | °C |

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

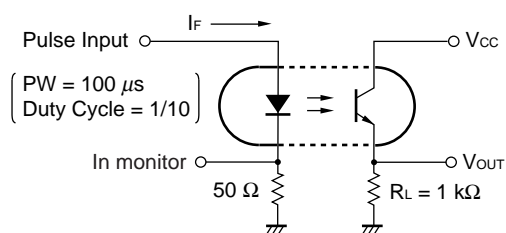
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

| Parameter | | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|------------|---|----------------------|---|------------------|------|------|------|
| Diode | Forward Voltage | V _F | I _F = 5 mA | | 1.1 | 1.4 | V |
| | Reverse Current | I _R | V _R = 5 V | | | 5 | μA |
| | Terminal Capacitance | C _t | V = 0 V, f = 1 MHz | | 30 | | pF |
| Transistor | Collector to Emitter Dark Current | I _{CEO} | I _F = 0 mA, V _{CE} = 120 V | | | 100 | nA |
| Coupled | Current Transfer Ratio (I _c /I _F) ^{*1} | CTR | I _F = 5 mA, V _{CE} = 5 V | 50 | 150 | 400 | % |
| | | | I _F = 1 mA, V _{CE} = 5 V | 10 | 80 | | |
| | Collector Saturation Voltage | V _{CE(sat)} | I _F = 10 mA, I _c = 2 mA | | | 0.3 | V |
| | Isolation Resistance | R _{I-O} | V _{I-O} = 1 kV _{DC} | 10 ¹¹ | | | Ω |
| | Isolation Capacitance | C _{I-O} | V = 0 V, f = 1 MHz | | 0.4 | | pF |
| | Rise Time ^{*2} | t _r | V _{CC} = 5 V, I _c = 2 mA, R _L = 1 kΩ | | 10 | | μs |
| | Fall Time ^{*2} | t _f | | | 10 | | |

*1 CTR rank

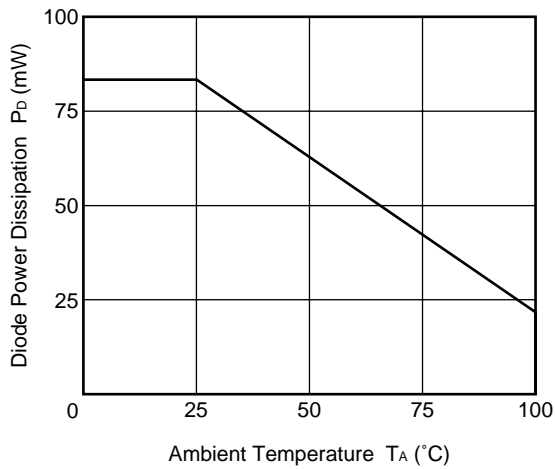
| CTR rank | CTR (%) | Conditions |
|----------|------------|--|
| K | 200 to 400 | I _F = 5 mA, V _{CE} = 5 V |
| | 80 to | I _F = 1 mA, V _{CE} = 5 V |
| L | 100 to 300 | I _F = 5 mA, V _{CE} = 5 V |
| | 25 to | I _F = 1 mA, V _{CE} = 5 V |
| M | 50 to 150 | I _F = 5 mA, V _{CE} = 5 V |
| | 10 to | I _F = 1 mA, V _{CE} = 5 V |

*2 Test circuit for switching time

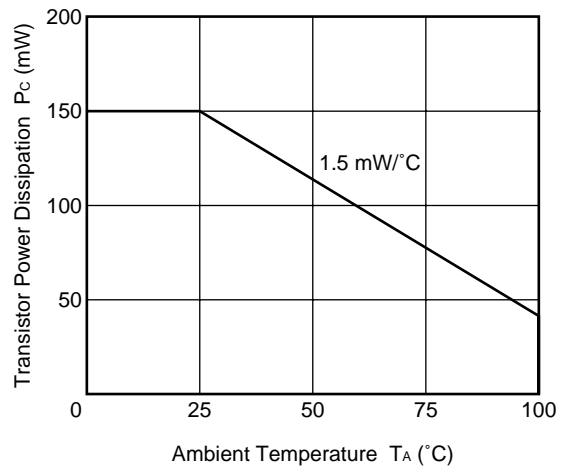


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

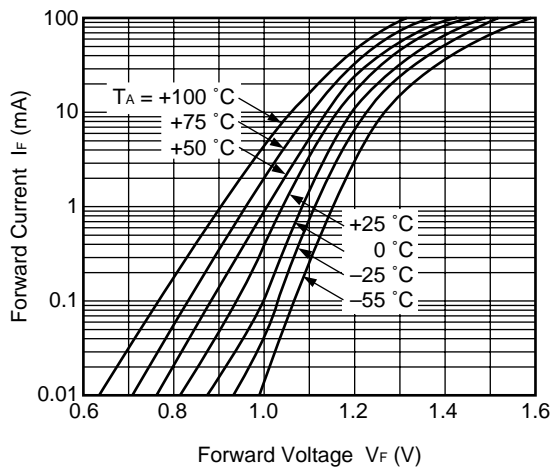
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



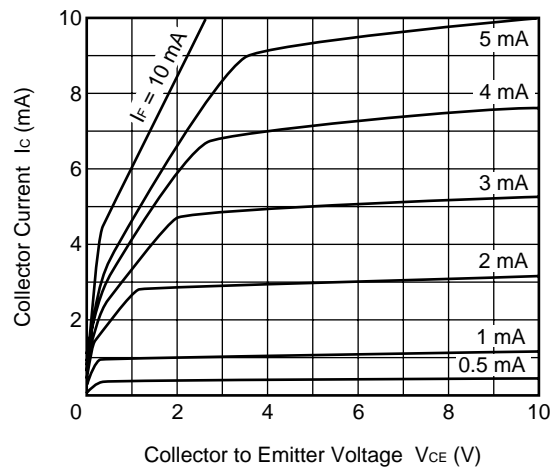
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



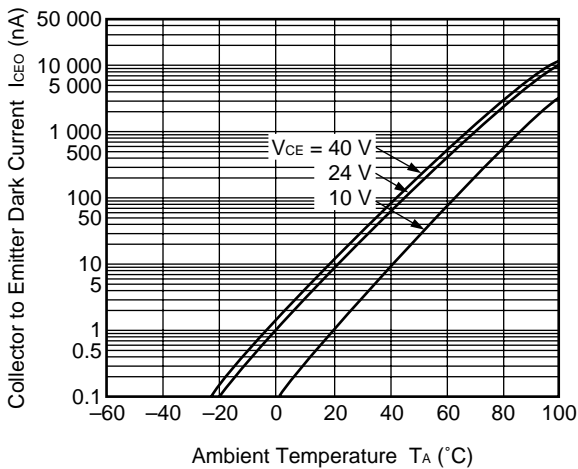
FORWARD CURRENT vs. FORWARD VOLTAGE



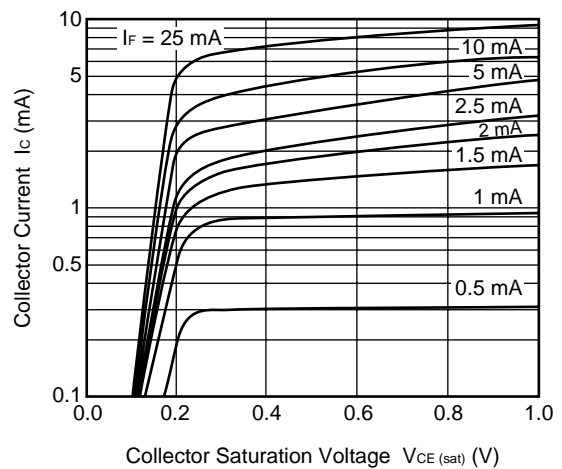
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

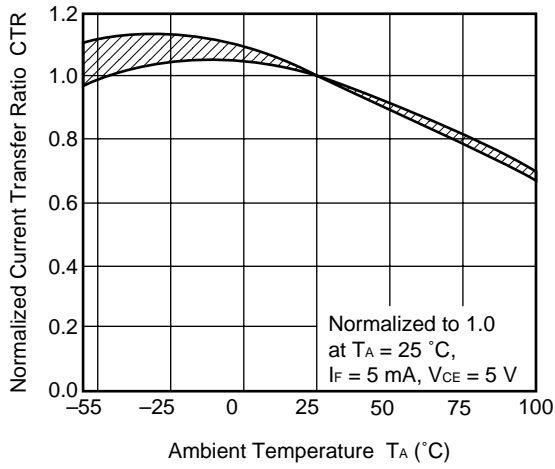


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

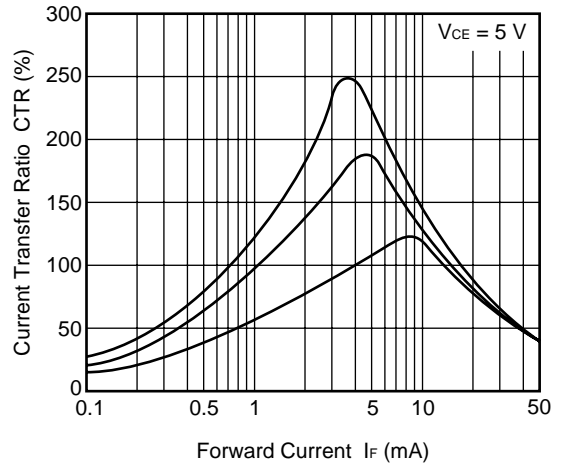


Remark The graphs indicate nominal characteristics.

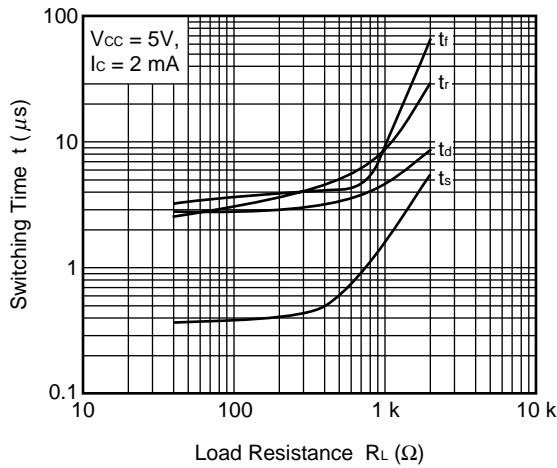
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



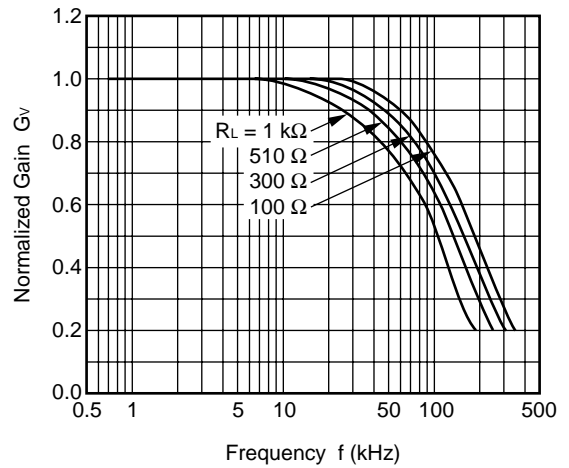
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



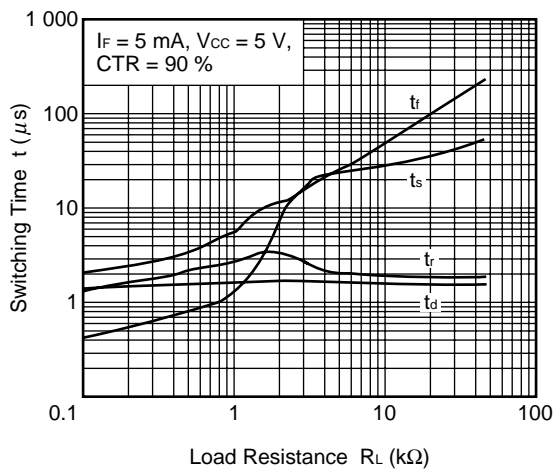
SWITCHING TIME vs. LOAD RESISTANCE



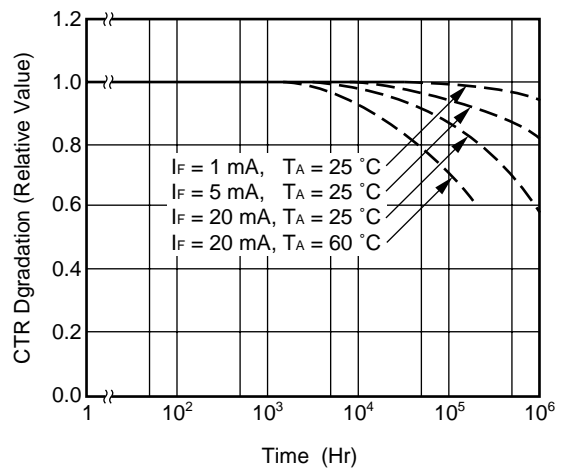
FREQUENCY RESPONSE



SWITCHING TIME vs. LOAD RESISTANCE



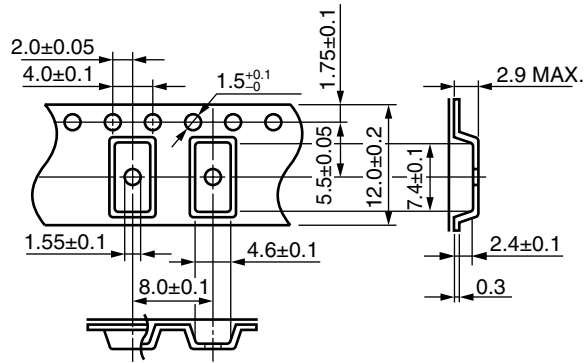
LONG TIME CTR DEGRADATION



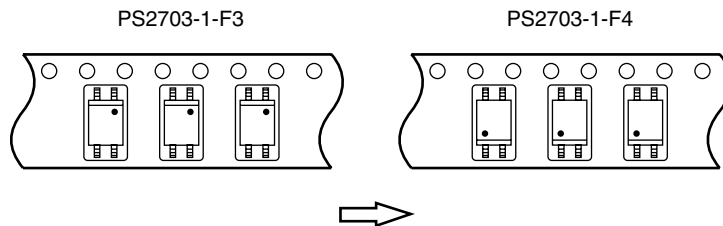
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

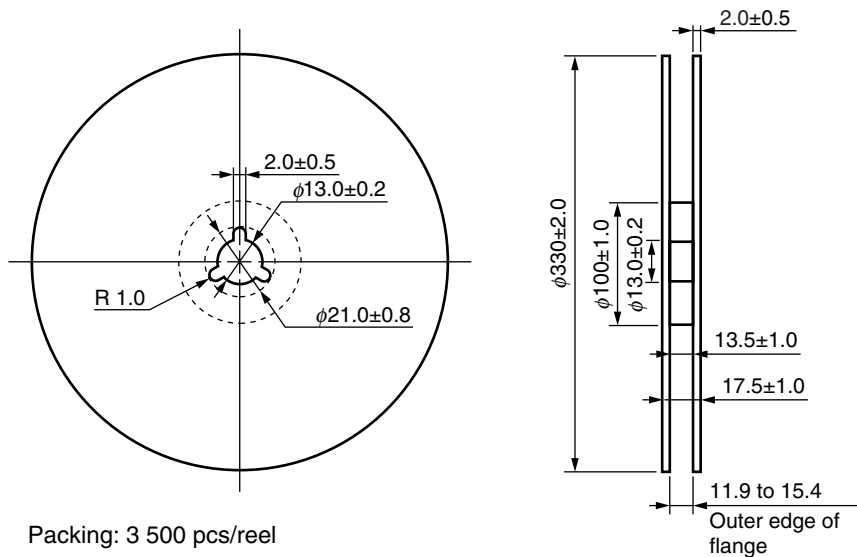
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



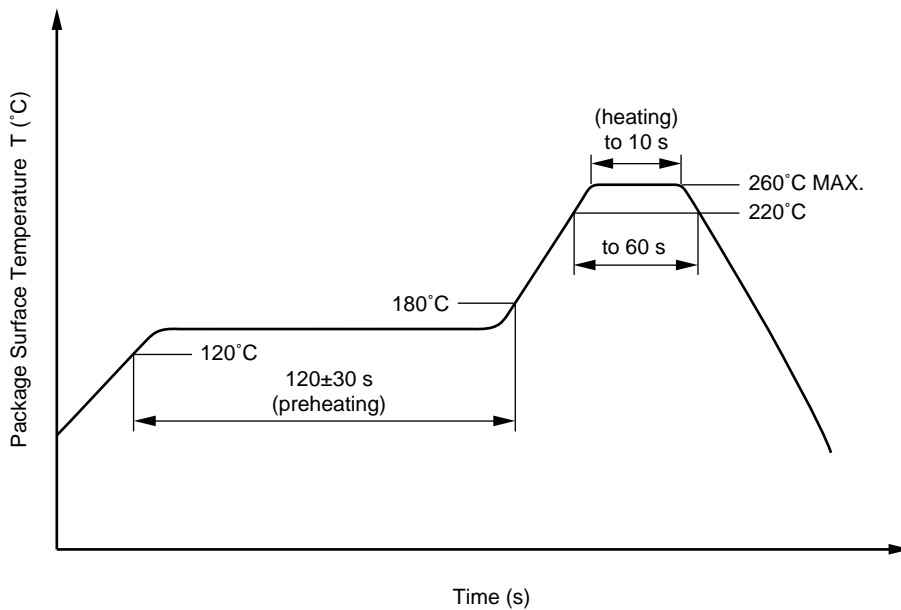
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ **(3) Soldering by soldering iron**

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (VDE0884)

| Parameter | Symbol | Speck | Unit |
|--|--|-----------------------------|----------------------------|
| Application classification (DIN VDE 0109) for rated line voltages ≤ 300 Vr.m.s. for rated line voltages ≤ 600 Vr.m.s. | | IV III | |
| Climatic test class (DIN IEC 68 Teil 1/09.80) | | 55/100/21 | |
| Dielectric strength maximum operating isolation voltage. Test voltage (partial discharge test procedure a for type test and random test) $U_{pr} = 1.2 \times U_{IORM}, P_d < 5$ pC | U_{IORM} U_{pr} | 710 850 | V_{peak} V_{peak} |
| Test voltage (partial discharge test procedure b for all devices test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5$ pC | U_{pr} | 1 140 | V_{peak} |
| Highest permissible overvoltage | U_{TR} | 6 000 | V_{peak} |
| Degree of pollution (DIN VDE 0109) | | 2 | |
| Clearance distance | | > 5 | mm |
| Creepage distance | | > 5 | mm |
| Comparative tracking index (DIN IEC 112/VDE 0303 part 1) | CTI | 175 | |
| Material group (DIN VDE 0109) | | III a | |
| Storage temperature range | T_{stg} | -55 to +150 | °C |
| Operating temperature range | T_A | -55 to +100 | °C |
| Isolation resistance, minimum value $V_{IO} = 500$ V dc at $T_A = 25$ °C $V_{IO} = 500$ V dc at T_A MAX. at least 100 °C | Ris MIN. Ris MIN. | 10^{12} 10^{11} | Ω Ω |
| Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current $I_F, P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500$ V dc at $T_A = 175$ °C (T_{si}) | T_{si} I_{si} P_{si} Ris MIN. | 150 200 300 10^9 | °C mA mW Ω |

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M8E 00.4-0110

| | | |
|-----------------------|----------------------|---|
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|-----------------------|----------------------|---|

► For further information, please contact

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